

April 2000

# **FQB5N60 / FQI5N60**

# **600V N-Channel MOSFET**

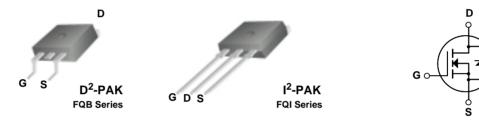
# **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

#### **Features**

- 5.0A, 600V,  $R_{DS(on)} = 2.0\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 16 nC)
- Low Crss (typical 9.0 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQB5N60 / FQI5N60	Units
V <sub>DSS</sub>	Drain-Source Voltage		600	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		5.0	Α
	- Continuous (T <sub>C</sub> = 100°C)	)	3.15	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	20	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	300	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	5.0	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		3.13	W
	Power Dissipation (T <sub>C</sub> = 25°C)		120	W
	- Derate above 25°C		0.96	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

# **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.04	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.6		V/°C
I <sub>DSS</sub>	Zoro Coto Voltogo Proin Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V			10	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C			100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5 A		1.57	2.0	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_D = 2.5 \text{ A}$ (Note 4)		4.0		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		560 80 9	730 100 12	pF pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance			9	12	pF
Switch	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 5.0 A,		13	35	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		45	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	1.13 25		35	80	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		40	90	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 480 V, I <sub>D</sub> = 5.0 A,		16	20	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		3.5		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		7.8		nC
Drain-9	Source Diode Characteristics ar	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				5.0	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				20	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 5.0 \text{ A}$			1.4	V
			+		<b>—</b>	<b>+</b>
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 5.0 \text{ A},$		270		ns

# **Typical Characteristics**

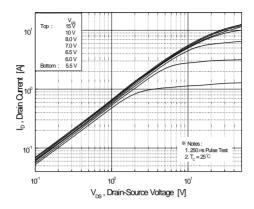


Figure 1. On-Region Characteristics

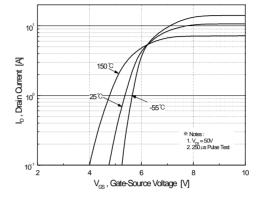


Figure 2. Transfer Characteristics

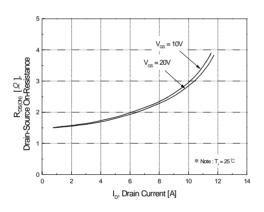


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

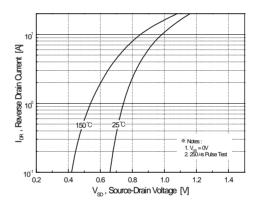


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

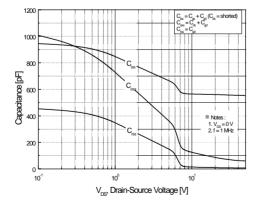


Figure 5. Capacitance Characteristics

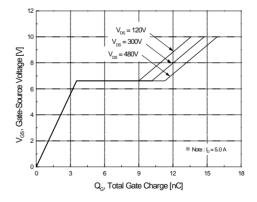
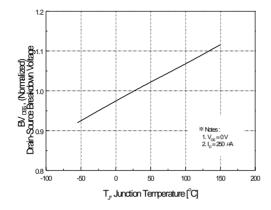


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)



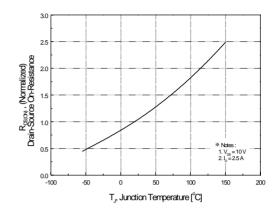
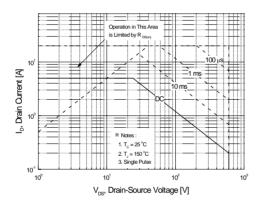


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



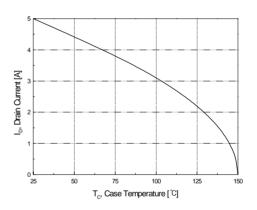


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

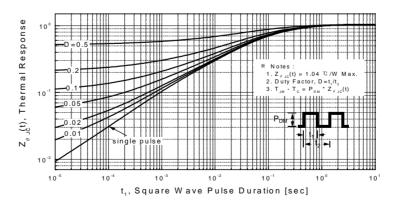
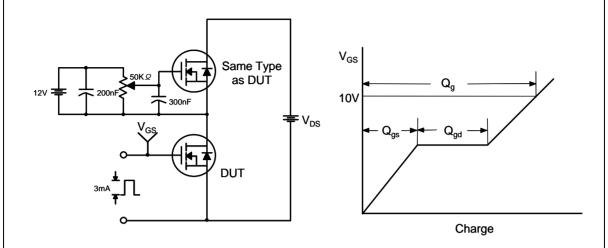


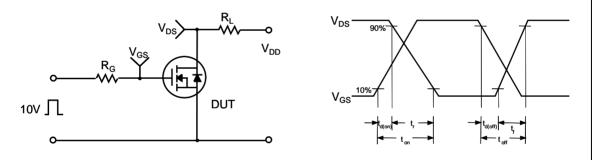
Figure 11. Transient Thermal Response Curve

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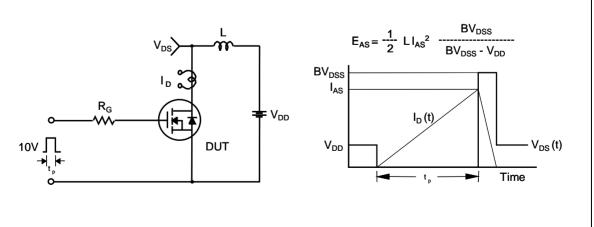
# **Gate Charge Test Circuit & Waveform**



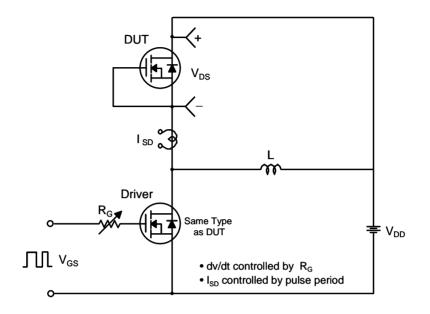
# **Resistive Switching Test Circuit & Waveforms**

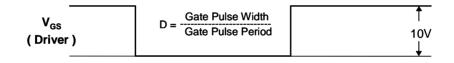


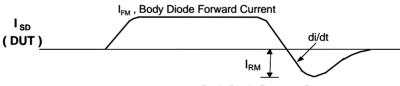
# **Unclamped Inductive Switching Test Circuit & Waveforms**



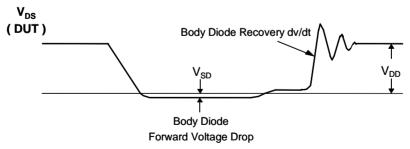
# Peak Diode Recovery dv/dt Test Circuit & Waveforms



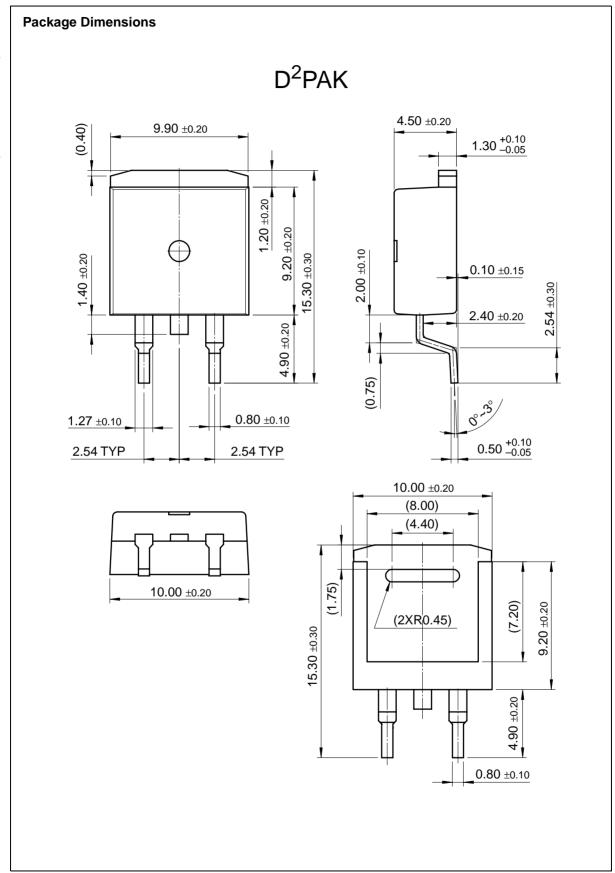


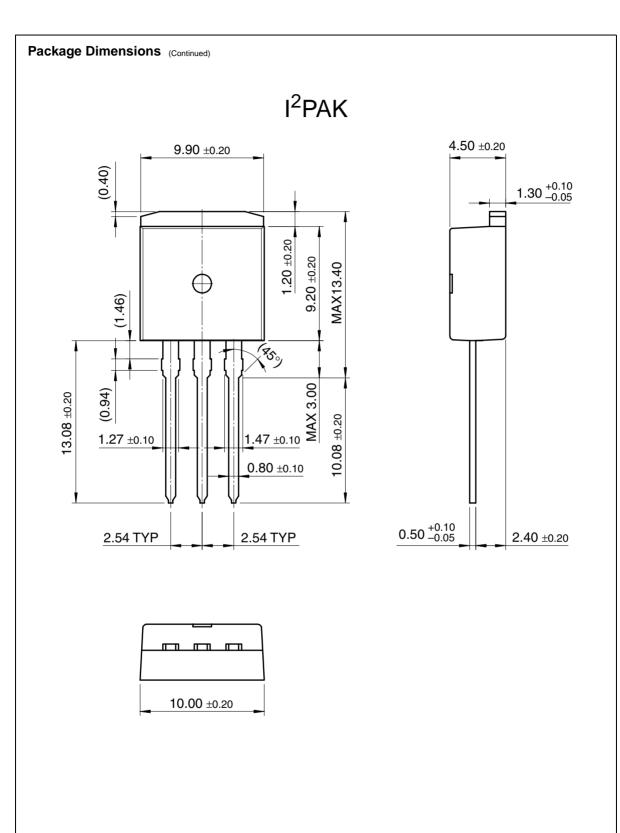


Body Diode Reverse Current



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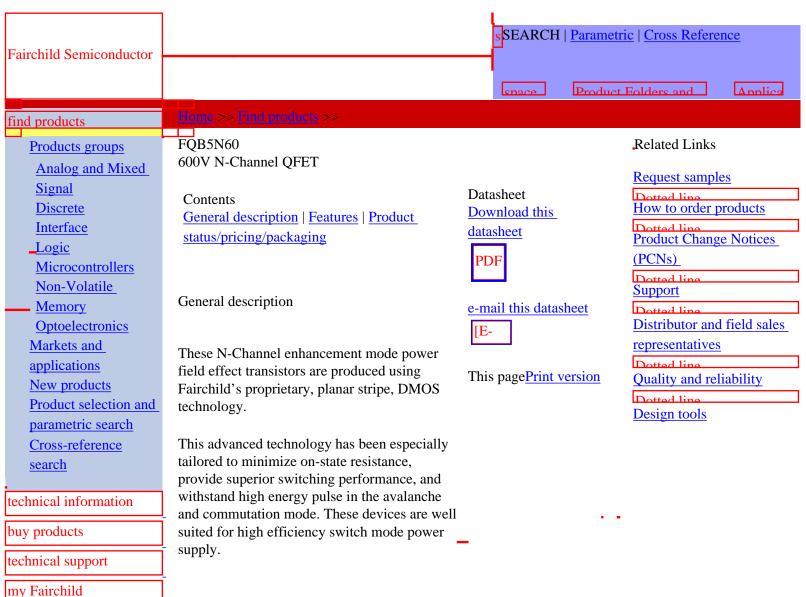
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## Features

company

- 5.0A, 600 V.  $R_{DS(ON)} = 2.0 \Omega$  @  $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 16 nC).
- Low Crss (typical 9.0 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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### Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB5N60TM	Full Production	\$0.94	TO-263(D2PAK)	2	TAPE REEL

\* 1,000 piece Budgetary Pricing

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